BLC9H10XS-60P

Power LDMOS transistor

AMPLEON

Rev. 2 — 29 May 2018

Product data sheet

1. Product profile

1.1 General description

60 W LDMOS packaged symmetric power transistor for base station applications at frequencies from 400 MHz to 1000 MHz.

Table 1. Typical performance 940 MHz

Typical RF performance at T_{case} = 25 °C in a class-AB demo circuit. V_{DS} = 50 V; I_{Dq} = 115 mA (per section).

Te	est signal	f	V _{DS}	P_L	G _p	η_{D}	ACPR
		(MHz)	(V)	(dBm)	(dB)	(%)	(dBc)
1-	carrier W-CDMA	925 to 960	50	35	16.5	13	-47 <u>[1]</u>

^[1] Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.9 dB at 0.01% probability on CCDF.

Table 2. Typical performance 859 MHz

Typical RF performance at T_{case} = 25 °C in a class-AB demo circuit. V_{DS} = 48 V; I_{Dq} = 125 mA (per section).

Test signal	f	V _{DS}	P_L	G _p	η _D	ACPR
	(MHz)	(V)	(dBm)	(dB)	(%)	(dBc)
1-carrier W-CDMA	785 to 960	48	35	16.1	11.9	-46.6 [<u>1</u>]

^[1] Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.9 dB at 0.01% probability on CCDF.

1.2 Features and benefits

- Easy power control
- Integrated ESD protection
- Excellent ruggedness
- High efficiency
- Excellent thermal stability
- Designed for broadband operation (400 MHz to 1000 MHz)
- For RoHS compliance see the product details on the Ampleon website

1.3 Applications

RF power amplifiers for base stations and multi carrier applications in the 400 MHz to 1000 MHz frequency range

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Graphic symbol
1	drain1		
2	drain2		1
3	gate1		3
4	gate2		5
5	source [1]		4 7
		3 4	2 sym117

[1] Connected to flange.

3. Ordering information

Table 4. Ordering information

Type number	Package	Package					
	Name Description Ve						
BLC9H10XS-60P	-	air cavity plastic earless flanged package; 4 leads	SOT1273-1				

4. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage			-	105	V
V_{GS}	gate-source voltage			-6	+11	V
T _{stg}	storage temperature			-65	+150	°C
Tj	junction temperature		[1]	-	225	°C
T _{case}	case temperature	operating	[1]	-40	+125	°C

^[1] Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

5. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
ti i(j-c)		V_{DS} = 50 V; I_{Dq} = 115 mA (per section); T_{case} = 80 °C; P_{L} = 3.16 W	8.0	K/W

6. Characteristics

Table 7. DC characteristics

 T_i = 25 °C; per section unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
V _{(BR)DSS}	drain-source breakdown voltage	$V_{GS} = 0 \text{ V}; I_D = 0.22 \text{ mA}$	105	-	-	V
V _{GS(th)}	gate-source threshold voltage	V _{DS} = 10 V; I _D = 22 mA	1.5	2.0	2.5	V
V_{GSq}	gate-source quiescent voltage	V _{DS} = 50 V; I _D = 110 mA	-	2.2	-	V
I _{DSS}	drain leakage current	V _{GS} = 0 V; V _{DS} = 50 V	-	-	1.4	μΑ
I _{DSX}	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V};$ $V_{DS} = 10 \text{ V}$	-	3.6	-	Α
I _{GSS}	gate leakage current	V _{GS} = 11 V; V _{DS} = 0 V	-	-	140	nA
9 _{fs}	forward transconductance	V _{DS} = 10 V; I _D = 1.1 A	-	1.5	-	S
R _{DS(on)}	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 V;$ $I_D = 0.77 A$	-	1070	1328	mΩ

Table 8. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH; f_1 = 929.5 MHz; f_2 = 954.5 MHz; RF performance at V_{DS} = 50 V; I_{Dq} = 110 mA; T_{case} = 25 °C; unless otherwise specified; in a class AB production test circuit at frequencies from 927 MHz to 957 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Gp	power gain	P _{L(AV)} = 3.2 W	15.3	16.3	-	dB
RLin	input return loss	P _{L(AV)} = 3.2 W	-	-24	-17	dB
η_{D}	drain efficiency	P _{L(AV)} = 3.2 W	11.5	12.5	-	%
ACPR	adjacent channel power ratio	P _{L(AV)} = 3.2 W	-	-49	-44	dBc

Table 9. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH; f = 929.5 MHz; RF performance at V_{DS} = 50V; I_{Dq} = 110 mA; T_{case} = 25 °C; unless otherwise specified; in a class AB production test circuit at frequencies from 927 MHz to 957 MHz.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
PARO	output peak-to-average ratio	P _{L(AV)} = 17.4 W	6.1	6.8	-	dB
$P_{L(M)}$	peak output power	P _{L(AV)} = 17.4 W	70	102	-	W

7. Test information

7.1 Ruggedness in class-AB operation

The BLC9H10XS-60P is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:

- $V_{DS} = 52 \text{ V}$; $I_{Dq} = 115 \text{ mA}$ (per section); f = 925 MHz; $P_L = 19 \text{ W}$; 1T-W-CDMA
- V_{DS} = 52 V; I_{Dq} = 115 mA (per section); f = 925 MHz; P_L = 60 W; pulsed CW (t_p = 100 μ s; δ = 10 %)

7.2 Impedance information

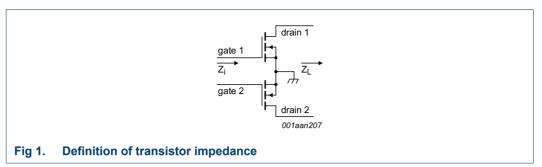
Table 10. Typical impedance of main device

Measured load-pull data of main device; I_{Dq} = 110 mA (per section); V_{DS} = 50 V; pulsed CW (t_D = 100 μ s; δ = 10 %).

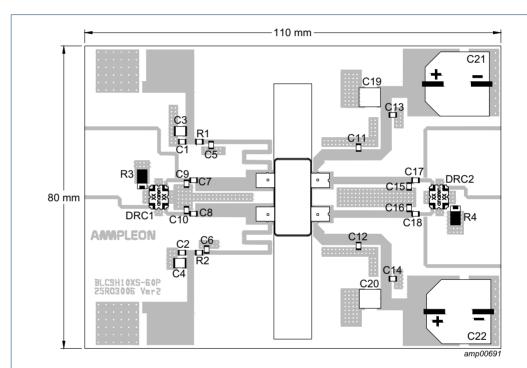
f	Z _S [1]	Z _L [1]	P _L [2]	η _D [2]	G _p [2]
(MHz)	(Ω)	(Ω)	(W)	(%)	(dB)
Maximum	power load	'			
600	4.81 + j13.6	21.86 – j0.92	55.1	62.9	16.8
698	4.97 + j11.1	13.94 + j3.05	46.8	55.7	15.3
720	4.93 + j10.6	14.52 + j5.94	49.2	62.9	15.9
746	4.93 + j10.1	13.04 + j7.01	49.3	64.3	15.8
757	4.97 + j9.96	10.67 + j6.38	50.9	62.0	15.2
769	4.98 + j9.75	11.88 + j5.04	52.0	61.6	15.0
790	4.95 + j9.32	16.62 + j4.46	51.8	63.4	15.1
800	4.96 + j9.11	16.68 + j4.43	51.5	63.1	14.9
820	4.86 + j8.73	15.09 + j5.39	49.7	62.7	14.9
869	4.83 + j7.86	15.02 + j4.25	48.0	58.8	14.0
880	4.76 + j7.64	17.58 + j5.87	47.8	60.5	14.3
894	4.76 + j7.41	15.40 + j4.05	46.6	57.2	13.8
925	4.64 + j6.90	14.04 + j6.92	45.5	60.2	14.1
942	4.59 + j6.55	14.94 + j6.98	45.4	59.8	13.9
960	4.55 + j6.23	11.33 + j6.56	45.8	59.7	13.6
1000	4.46 + j5.57	11.26 + j6.49	46.6	60.8	13.3
Maximum	drain efficiency load				-
600	4.78 + j13.50	25.42 + j5.49	51.0	68.5	17.9
698	4.89 + j10.98	21.35 + j17.90	34.0	66.5	17.9
720	4.85 + j10.57	17.70 + j13.04	39.6	67.5	17.2
746	4.80 + j10.02	14.55 + j15.59	34.5	68.6	17.6
757	4.78 + j9.79	12.05 + j15.07	34.6	70.0	17.5
769	4.74 + j9.57	12.02 + j15.05	35.0	70.5	17.6
800	4.72 + j9.14	11.18 + j14.21	35.9	71.4	17.2
805	4.71 + j8.92	11.20 + j14.23	35.3	71.0	17.1
820	4.64 + j8.56	11.08 + j14.07	34.3	68.5	17.0
869	4.52 + j7.57	7.82 + j16.59	24.0	68.2	17.5
880	4.51 + j7.45	8.69 + j13.51	33.1	68.1	16.5
894	4.47 + j7.17	8.51 + j14.09	31.4	68.0	16.6
925	4.41 + j6.71	8.50 + j14.03	32.6	69.0	16.4
942	4.36 + j6.34	8.44 + j14.04	32.3	68.5	16.2
960	4.27 + j6.01	7.19 + j13.36	31.9	69.4	16.2
1000	4.17 + j5.32	7.17 + j13.26	31.7	69.9	16.1

^[1] Z_S and Z_L defined in Figure 1.

^[2] At 3 dB gain compression.



7.3 Test circuit



Printed-Circuit Board (PCB): RO3006: ϵ_r = 6.15; thickness = 0.635 mm; thickness copper plating = 35 μ m. See Table 11 for a list of components.

Fig 2. Component layout

Table 11. List of components See Figure 2 for component layout.

Component	Description	Value	Remarks
C1, C2	multilayer ceramic chip capacitor	10 nF, 50 V	Murata: Hi-Q SMD 0805
C3, C4	multilayer ceramic chip capacitor	4.7 μF, 50 V	Murata: Hi-Q SMD 1210
C5, C6, C7, C8, C13, C14, C17, C18	multilayer ceramic chip capacitor	82 pF, 250 V	Murata: Hi-Q SMD 0805
C9, C10	multilayer ceramic chip capacitor	9.1 pF, 250 V	Murata: Hi-Q SMD 0805
C11, C12	multilayer ceramic chip capacitor	2 pF, 250 V	Murata: Hi-Q SMD 0805
C15, C16	multilayer ceramic chip capacitor	4.3 pF, 250 V	Murata: Hi-Q SMD 0805
C19, C20	multilayer ceramic chip capacitor	4.7 μF, 100V	Murata: Hi-Q SMD 2220

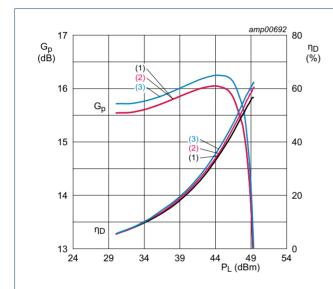
Table 11. List of components ...continued

See Figure 2 for component layout.

Component	Description	Value	Remarks
C21, C22	electrolytic capacitor	470 μF, 100 V	Panasonic: FK series
R1, R2	resistor	5.6 Ω, 1/6 W	SMD 0805
R3, R4	resistor	50 Ω, 16 W	Anaren: C16A50Z4
DRC1, DRC2	hybrid coupler	3 dB, 90°	Anaren: X3C09F1-03S

7.4 Graphical data

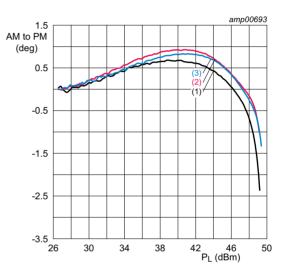
7.4.1 Pulsed CW



 V_{DS} = 50 V; I_{Dq} = 115 mA; t_p = 100 $\mu s; \, \delta$ = 10 %.

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 3. Power gain and drain efficiency as function of output power; typical values



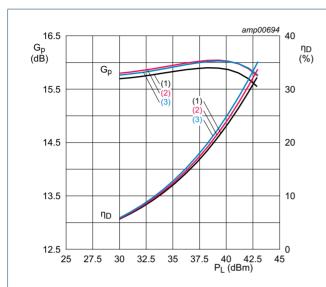
 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 4. Normalized AM to PM as a function of output power; typical values

7.4.2 1-Carrier W-CDMA

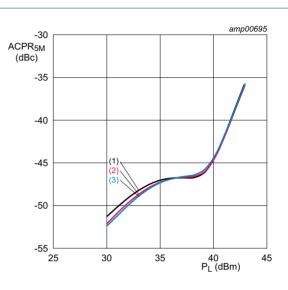
Test signal: 3GPP test model 1; 1 to 64 DPCH (100 % clipping): PAR = 9.9 dB per carrier at 0.01 % probability on CCDF per carrier.



 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

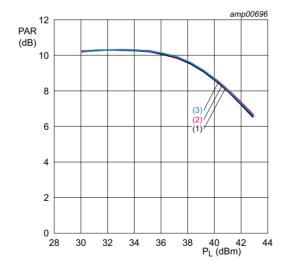
Fig 5. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 6. Adjacent channel power ratio (5 MHz) as a function of output power; typical values



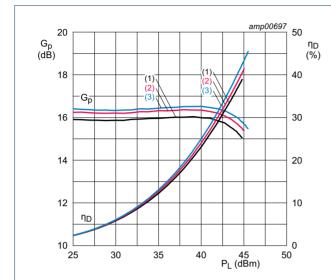
 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 7. Peak-to-average power ratio as a function of output power; typical values

7.4.3 2-Carrier W-CDMA

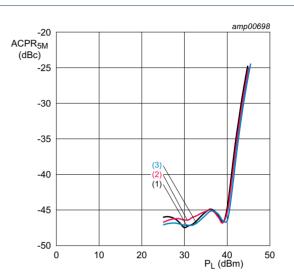
Test signal: 3GPP test model 1; 1 to 64 DPCH (46 % clipping, 5 MHz spacing).



 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 8. Power gain and drain efficiency as function of output power; typical values

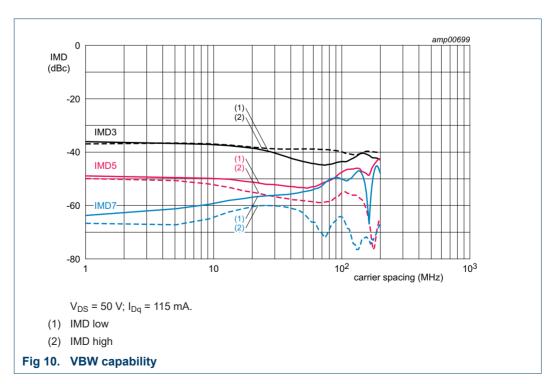


 $V_{DS} = 50 \text{ V}; I_{Dq} = 115 \text{ mA}.$

- (1) f = 925 MHz
- (2) f = 942.5 MHz
- (3) f = 960 MHz

Fig 9. Adjacent channel power ratio (5 MHz) as a function of output power; typical values

7.4.4 2-Tone VBW



8. Package outline

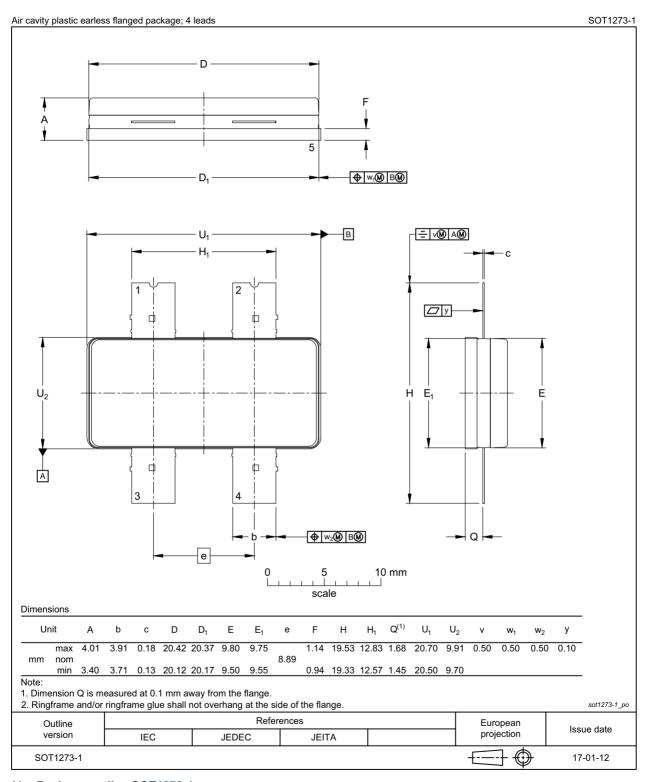


Fig 11. Package outline SOT1273-1

9. Handling information

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 12. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C3 [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C3 is granted to any part that passes after exposure to an ESD pulse of ≥ 1000 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V.

10. Abbreviations

Table 13. Abbreviations

Acronym	Description		
3GPP	3rd Generation Partnership Project		
CCDF	Complementary Cumulative Distribution Function		
CW	Continuous Wave		
DPCH	Dedicated Physical CHannel		
ESD	ElectroStatic Discharge		
LDMOS	Laterally Diffused Metal-Oxide Semiconductor		
MTF	Median Time to Failure		
PAR	Peak-to-Average Ratio		
RoHS	Restriction of Hazardous Substances		
SMD	Surface Mounted Device		
VBW	Video BandWidth		
VSWR	Voltage Standing Wave Ratio		
W-CDMA	Wideband Code Division Multiple Access		

11. Revision history

Table 14. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BLC9H10XS-60P v.2	20180529	Product data sheet	-	BLC9H10XS-60P v.1
Modifications	 Table 1 on page 1: updated table note Table 2 on page 1: updated table Section 7.1 on page 3: updated first list item 			
	Section 7.4.2 on page 7: updated first paragraph			
	removed section 7.4.5. Group delay			
	<u>Table 12 on page 10</u> : updated table			
BLC9H10XS-60P v.1	20180501	Preliminary data sheet	-	-

12. Legal information

12.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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AMPLEON

BLC9H10XS-60P

Power LDMOS transistor

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